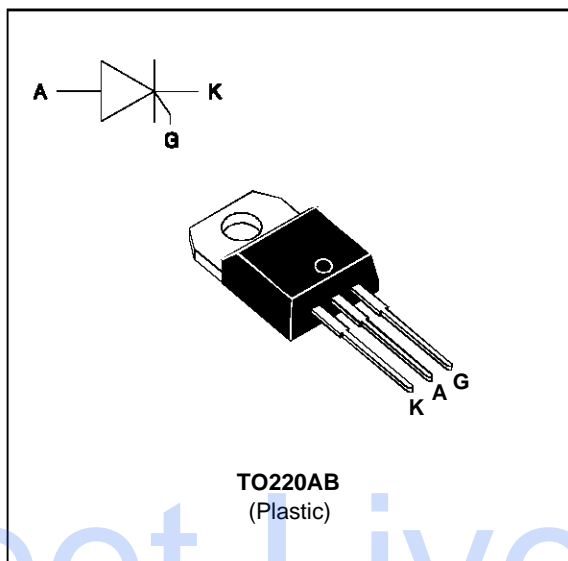


**FEATURES**

- HIGH SURGE CAPABILITY
- HIGH ON-STATE CURRENT
- HIGH STABILITY AND RELIABILITY
- TXN Serie :  
INSULATED VOLTAGE = 2500V<sub>(RMS)</sub>  
(UL RECOGNIZED : E81734)

**DESCRIPTION**

The TYN/TXN 058 ---> TYN/TXN 1008 Family of Silicon Controlled Rectifiers uses a high performance glass passivated chips technology. This general purpose Family of Silicon Controlled Rectifiers is designed for power supplies up to 400Hz on resistive or inductive load.



**ABSOLUTE RATINGS** (limiting values)

| Symbol                             | Parameter   |            | Value  | Unit                           |                  |
|------------------------------------|---|------------|--|--------------------------------|------------------|
| I <sub>T(RMS)</sub>                | RMS on-state current<br>(180° conduction angle)   | TXN<br>TYN | T <sub>c</sub> =100°C<br>T <sub>c</sub> =105°C | 8<br>A                         |                  |
| I <sub>T(AV)</sub>                 | Average on-state current<br>(180° conduction angle, single phase circuit)                                       | TXN<br>TYN | T <sub>c</sub> =100°C<br>T <sub>c</sub> =105°C | 5<br>A                         |                  |
| I <sub>TSM</sub>                   | Non repetitive surge peak on-state current<br>( T <sub>j</sub> initial = 25°C )                                 |            | tp=8.3 ms                                      | 84                             | A                |
|                                    |   |            | tp=10 ms                                       | 80                             |                  |
| I <sup>2</sup> t                   | I <sup>2</sup> t value  |            | tp=10 ms                                       | 32                             | A <sup>2</sup> s |
| di/dt                              | Critical rate of rise of on-state current<br>Gate supply : I <sub>G</sub> = 100 mA di <sub>G</sub> /dt = 1 A/μs |            |  | 50                             | A/μs             |
| T <sub>stg</sub><br>T <sub>j</sub> | Storage and operating junction temperature range  |            |  | - 40 to + 150<br>- 40 to + 125 | °C<br>°C         |
| T <sub>l</sub>                     | Maximum lead temperature for soldering during 10 s at 4.5 mm from case  |            |  | 260                            | °C               |

| Symbol                               | Parameter  | TYN/TXN |     |     |     |     |     |      | Unit |
|--------------------------------------|--|---------|-----|-----|-----|-----|-----|------|------|
|                                      |  | 058     | 108 | 208 | 408 | 608 | 808 | 1008 |      |
| V <sub>DRM</sub><br>V <sub>RRM</sub> | Repetitive peak off-state voltage<br>T <sub>j</sub> = 125 °C | 50      | 100 | 200 | 400 | 600 | 800 | 1000 | V    |

## TXN/TYN 058 (G) ---> TXN/TYN 1008 (G)

### THERMAL RESISTANCES

| Symbol       | Parameter               |     | Value | Unit |
|--------------|-------------------------|-----|-------|------|
| Rth (j-a)    | Junction to ambient     |     | 60    | °C/W |
| Rth (j-c) DC | Junction to case for DC | TXN | 3.5   | °C/W |
|              |                         | TYN | 2.5   |      |

### GATE CHARACTERISTICS (maximum values)

$P_G$  (AV) = 1W     $P_{GM}$  = 10W (tp = 20 μs)     $I_{FGM}$  = 4A (tp = 20 μs)     $V_{RGM}$  = 5 V.

### ELECTRICAL CHARACTERISTICS

| Symbol                 | Test Conditions   |                   |     | Value |     | Unit |
|------------------------|---|-------------------|-----|-------|-----|------|
|                        |   |                   |     | BLANK | G   |      |
| $I_{GT}$               | $V_D=12V$ (DC) $R_L=33\Omega$   | $T_j=25^\circ C$  | MAX | 15    | 25  | mA   |
| $V_{GT}$               | $V_D=12V$ (DC) $R_L=33\Omega$   | $T_j=25^\circ C$  | MAX | 1.5   |     | V    |
| $V_{GD}$               | $V_D=V_{DRM}$ $R_L=3.3k\Omega$  | $T_j=110^\circ C$ | MIN | 0.2   |     | V    |
| tgt                    | $V_D=V_{DRM}$ $I_G=40mA$<br>$dl_G/dt=0.5A/\mu s$  | $T_j=25^\circ C$  | TYP | 2     |     | μs   |
| $I_L$                  | $I_G=1.2 I_{GT}$  | $T_j=25^\circ C$  | TYP | 50    |     | mA   |
| $I_H$                  | $I_T=100mA$ gate open   | $T_j=25^\circ C$  | MAX | 30    | 45  | mA   |
| $V_{TM}$               | $I_{TM}=16A$ tp= 380μs  | $T_j=25^\circ C$  | MAX | 1.8   |     | V    |
| $I_{DRM}$<br>$I_{RRM}$ | $V_{DRM}$ Rated<br>$V_{RRM}$ Rated  | $T_j=25^\circ C$  | MAX | 0.01  |     | mA   |
|                        |   | $T_j=110^\circ C$ |     | 2     |     |      |
| dV/dt                  | Linear slope up to $V_D=67\%V_{DRM}$<br>gate open                                       | $T_j=110^\circ C$ | MIN | 200   | 500 | V/μs |
| tq                     | $V_D=67\%V_{DRM}$ $I_{TM}=16A$ $V_R=25V$<br>$dl_{TM}/dt=30 A/\mu s$ $dV_D/dt=50V/\mu s$ | $T_j=110^\circ C$ | TYP | 70    |     | μs   |

TXN/TYN 058 (G) ---> TXN/TYN 1008 (G)

| Package              | $I_{T(RMS)}$ | $V_{DRM} / V_{RRM}$ | Sensitivity Specification |   |
|----------------------|--------------|---------------------|---------------------------|---|
|                      | A            | V                   | BLANK                     | G |
| TXN<br>(Insulated)   | 8            | 50                  | X                         | X |
|                      |              | 100                 | X                         | X |
|                      |              | 200                 | X                         | X |
|                      |              | 400                 | X                         | X |
|                      |              | 600                 | X                         | X |
|                      |              | 800                 | X                         | X |
|                      |              | 1000                | X                         | X |
| TYN<br>(Uninsulated) |              | 50                  | X                         | X |
|                      |              | 100                 | X                         | X |
|                      |              | 200                 | X                         | X |
|                      |              | 400                 | X                         | X |
|                      |              | 600                 | X                         | X |
|                      |              | 800                 | X                         | X |
|                      |              | 1000                | X                         | X |

Fig.1 : Maximum average power dissipation versus average on-state current (TXN).

Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (TXN).

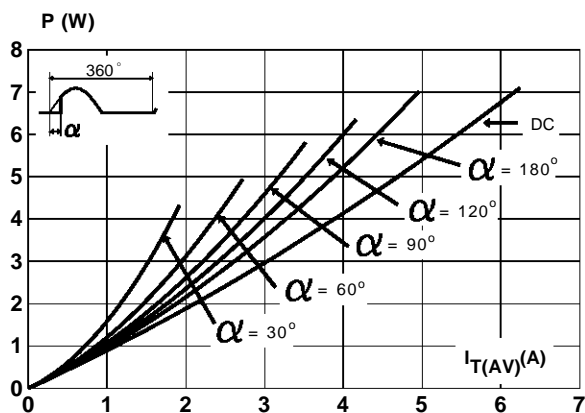


Fig.3 : Maximum average power dissipation versus average on-state current (TYN).

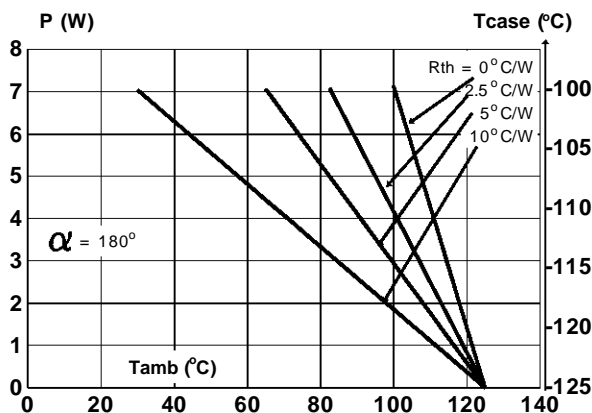
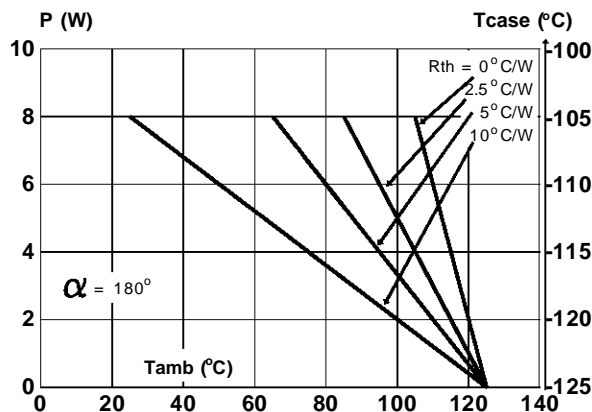
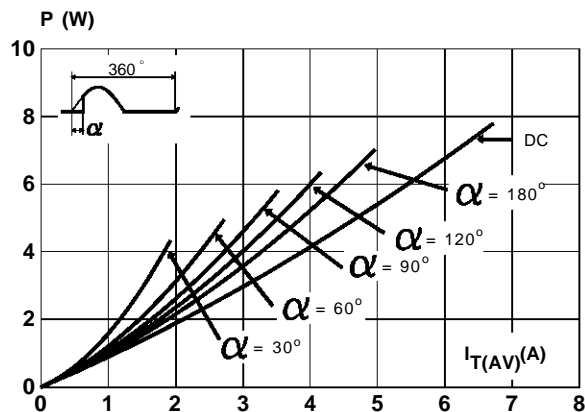
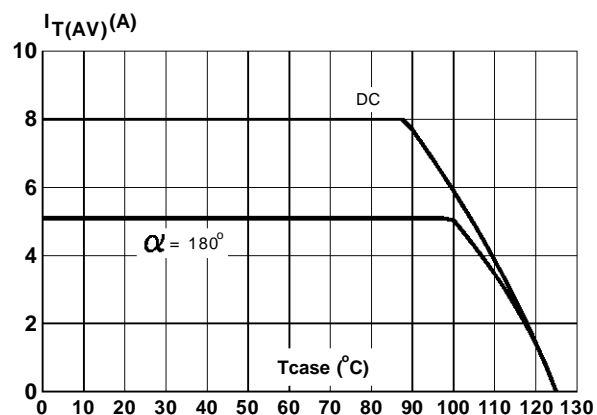


Fig.4 : Correlation between maximum average power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (TYN).

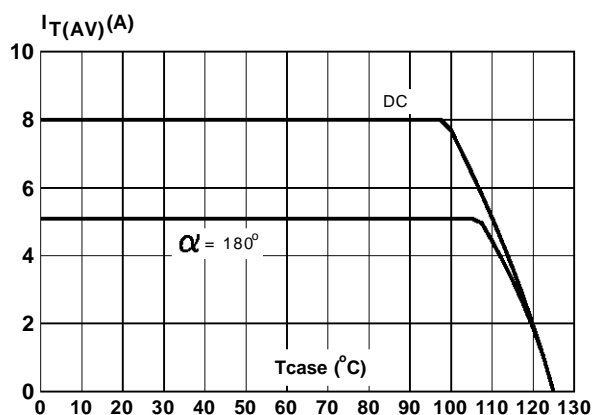


# TXN/TYN 058 (G) ---> TXN/TYN 1008 (G)

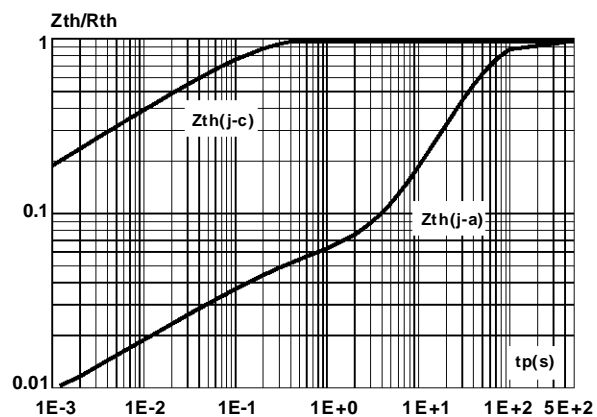
**Fig.5 :** Average on-state current versus case temperature (TXN).



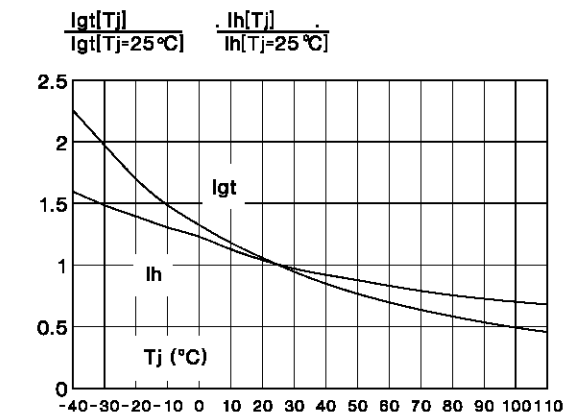
**Fig.6 :** Average on-state current versus case temperature (TYN).



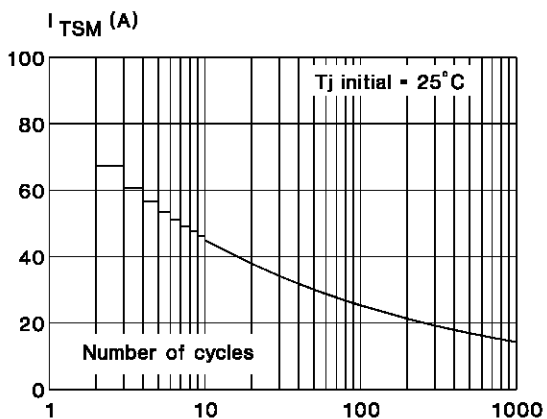
**Fig.7 :** Relative variation of thermal impedance versus pulse duration.



**Fig.8 :** Relative variation of gate trigger current versus junction temperature.



**Fig.9 :** Non repetitive surge peak on-state current versus number of cycles.



**Fig.10 :** Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .

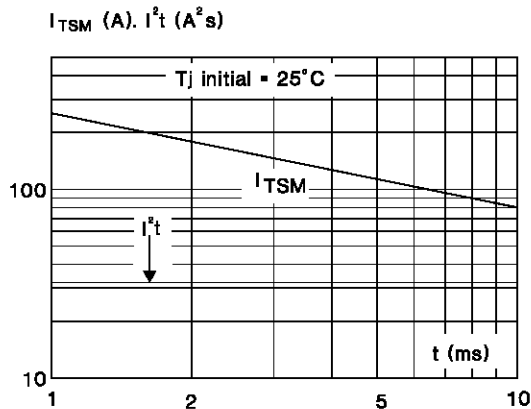
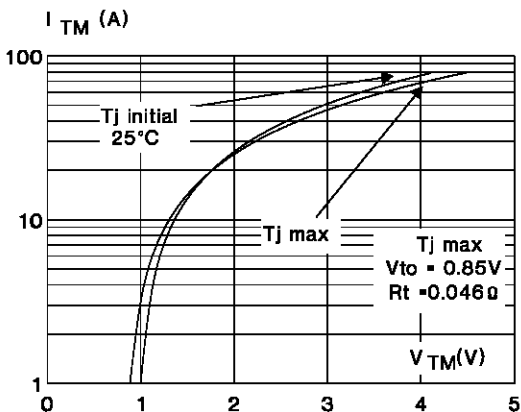
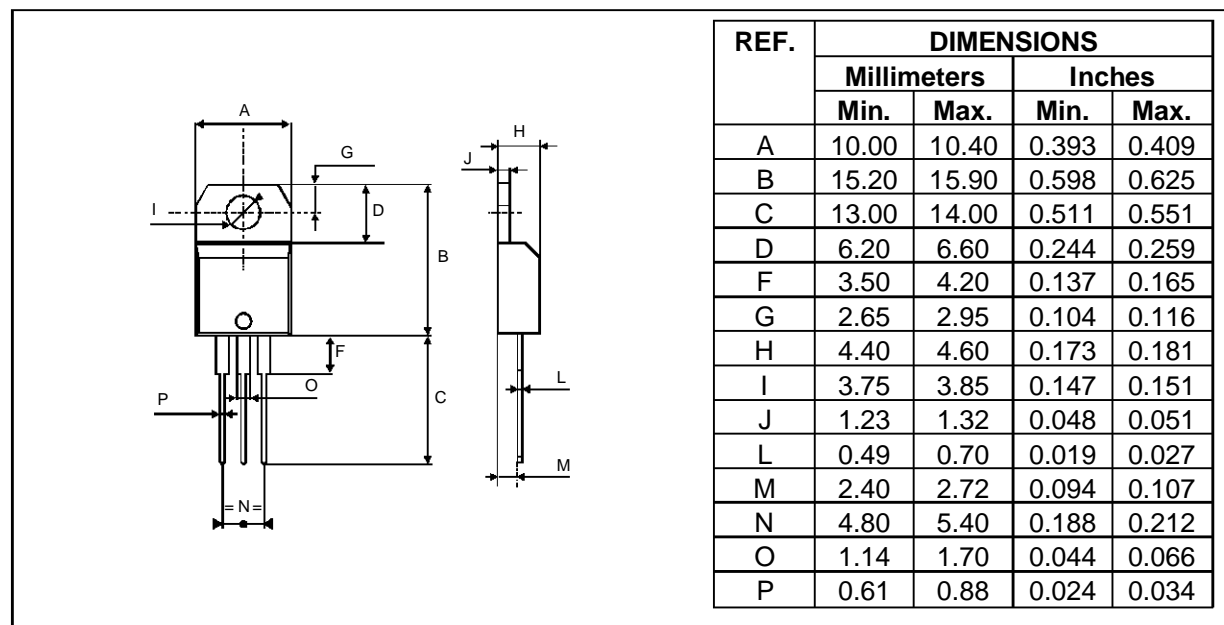


Fig.11 : On-state characteristics (maximum values).



**PACKAGE MECHANICAL DATA**

TO220AB Plastic



Cooling method : C  
 Marking : type number  
 Weight : 2.3 g

Recommended torque value : 0.8 m.N.  
 Maximum torque value : 1 m.N.

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